

| L Number | Hits    | Search Text  | DB  | Time stamp       |
|----------|---------|--|---|------------------|
| 1        | 61230   | 451/\$.cccls.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:26 |
| 2        | 1675290 | wafer or wafers or substrate or substrates   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:26 |
| 3        | 1459750 | drum or cylinder   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:26 |
| 4        | 65      | dressing with laser  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:26 |
| 5        | 18502   | (wafer or wafers or substrate or substrates ) with (drum or cylinder)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:28 |
| 6        | 379     | 451/\$.cccls. and ((wafer or wafers or substrate or substrates ) with (drum or cylinder))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:27 |
| 7        | 0       | (451/\$.cccls. and ((wafer or wafers or substrate or substrates ) with (drum or cylinder))) and (dressing with laser)                                | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:27 |
| 8        | 1       | ((wafer or wafers or substrate or substrates ) with (drum or cylinder)) and (dressing with laser)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:27 |
| 9        | 10474   | (wafer or wafers or substrate or substrates ) near5 (drum or cylinder)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:28 |
| 10       | 10474   | ((wafer or wafers or substrate or substrates ) near5 (drum or cylinder)) and ((wafer or wafers or substrate or substrates ) with (drum or cylinder)) | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:29 |
| 11       | 214     | ((wafer or wafers or substrate or substrates ) near5 (drum or cylinder)) and 451/\$.cccls.   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:29 |
| 12       | 294     | (451/254).CCLS.  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:39 |
| 13       | 23113   | rotary adj drum  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:40 |
| 14       | 1084    | (wafer or wafers or substrate or substrates ) and (rotary adj drum)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | 2003/01/14 10:40 |

|    |    |  |   |                  |
|----|----|--|---|------------------|
| 15 | 15 | ((wafer or wafers or substrate or substrates ) and (rotary adj drum)) and 451/\$.ccls. | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/01/14 10:40 |
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